C-14 – CONNECTORIZED HERMETIC MODULE

C-14 Package Outline Drawing

NOTES:
1. PACKAGE, LEADS, COVER MATERIAL: KOVAR TM
2. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
3. SPACER MATERIAL: NICKEL PLATED ALUMINUM
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. TOLERANCES ±0.010 [0.25] UNLESS OTHERWISE SPECIFIED
6. FIELD REPLACEABLE SMA CONNECTORS.
TENSOLITE 5602-5CCSF OR EQUIVALENT.